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(54) **Integrated electro-optical package**
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- **PROCEEDINGS OF THE ELECTRONIC COMPONENTS AND TECHNOLOGY CONFERENCE, ORLANDO, JUNE 1 - 4, 1993, no. CONF. 43, 1 June 1993 INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, pages 818-824, XP 000380084 MITSUO USUI ET AL 'NOVEL PACKAGING TECHNIQUE FOR LASER DIODE ARRAYS USING FILM CARRIER'**
- **IEEE TRANSACTIONS ON COMPONENTS, HYBRIDS, AND MANUFACTURING TECHNOLOGY, vol. 13, no. 3, 1 September 1990 pages 521-527, XP 000149633 KENZO HATADA ET AL 'LED ARRAY MODULES BY NEW TECHNOLOGY MICROBUMP BONDING METHOD'**
- **IBM TECHNICAL DISCLOSURE BULLETIN, vol. 26, no. 2, July 1983 NEW YORK, US, pages 572-574, ANONYMOUS 'Input/Output Device Interconnections'**

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Description

Field of the Invention

[0001] The present invention pertains to packages containing electrical and optical components connected in cooperation and more specifically to a package for electrically connecting optical components and driver circuits in electrical circuitry.

Background of the Invention

[0002] Generally, a semiconductor substrate, or integrated circuit, is mounted on a printed circuit board or the like and the accepted method for connecting the substrate to external circuits is to use standard wire bond technology. However, when a semiconductor substrate having a relatively large array of electrical components or devices formed thereon is to be connected, standard wire bond techniques can become very difficult. For example, if a relatively large array (greater than, for example, 10,000 or 100 x 100) of light emitting diodes is formed on a substrate with a pitch (center-to-center separation) of P, then bond pads on the perimeter of the substrate will have a 2P pitch. This is true because every other row and every other column goes to an opposite edge of the perimeter to increase the distance between bond pads as much as possible.

[0003] At the present time wire bond interconnects from bond pads having a pitch of 4.8 milli-inches (1 milli-inch = $2.54 \cdot 10^{-5}$ m) is the best that is feasible. Thus, in the array mentioned above of 100 x 100 light emitting diodes the bond pads on the perimeter of the semiconductor chip would have a minimum pitch of 4.8 milli-inches, with 50 bond pads situated along each edge of the perimeter. As more devices are included in the array, more bond pads are required and the perimeter size to accommodate the additional bond pads increases at an even greater rate. That is, since the minimum pitch of the bonding pads is 4.8 milli-inches, the pitch of the devices in the array can be as large as 2.4 milli-inches, or approximately 61 microns (1 micron = 10^{-6} m), without effecting the size of the substrate. Thus, even if the devices can be fabricated smaller than 61 microns, the minimum pitch of the bonding pads will not allow the perimeter of the substrate to be made any smaller. It can quickly be seen that the size of the substrate is severely limited by the limitations of the wire bonding technology.

[0004] Further, it has been common practice to mount substrates and interface circuitry on a single board. The problem that arises is the large amount of surface area required to mount and connect various components.

[0005] IBM Technical Disclosure Bulletin, vol. 26, No. 2, July 1983, "Input/Output Device Interconnections" by P.E.Cade et al. describes a device comprising a first semiconductor chip, in which light emitting diodes are formed, is mounted on, aligned and electrically interconnected with a second semiconductor chip, which may

be a driver chip, via appropriate solder balls or pads located in recesses in the second chip.

[0006] EP-A-0 572 779 describes a device comprising a semiconductor driver and a light emitting polymer element connected to the driver and formed integrally therewith into a light emitting element. One or more of the elements are included in a display pixel, and a plurality of pixels are arranged into rows and columns for a display source. The light emitting elements are also used as interconnects for semiconductor ICs.

[0007] Thus, there is a need for interconnect and packaging structures and techniques which can substantially reduce the limitation on size of substrate and which can reduce the amount of required surface area.

[0008] Accordingly, it is a purpose of the present invention to provide integrated electro-optical packages which are not limited in size by the electrical connections.

[0009] It is another purpose of the present invention to provide integrated electro-optical packages which are substantially smaller than previous integrated packages.

[0010] It is still another purpose of the present invention to provide integrated electro-optical packages which contain substantially greater numbers of light generating devices than previous integrated packages.

[0011] It is yet another purpose of the present invention to provide integrated electro-optical packages which contain arrays of light generating devices with substantially greater numbers of devices than previous integrated packages.

Summary of the Invention

[0012] The above problems and others are substantially solved and the above purposes and others are realized in an integrated electro-optical package according to claim 1 and to the fabrication method in claim 7 including an optically transparent substrate having a major surface with an array of light emitting devices formed on the major surface at a central portion thereof and cooperating to generate a complete real image. Each of the light emitting devices have first and second electrodes for activating the light emitting devices. The optically transparent substrate further has external connection/mounting pads adjacent outer edges thereof and outside of the central portion of the major surface with the first electrodes of the light emitting devices being connected to a first plurality of the external connection/mounting pads and the second electrodes of the light emitting devices being connected to a second plurality of the external connection/mounting pads. A driver substrate has a major surface and defines a central portion substantially coextensive with the real image at the central portion of the major surface of the optically transparent substrate. The driver substrate further has a plurality of electrical conductors formed therein, each extending from a mounting pad adjacent an edge of the

central portion to a connection pad on the major surface of the driver substrate. The optically transparent substrate can be, for example, formed of glass or some other suitable transparent material defining a central optically transparent light passage (window) therethrough with the electrical conductors formed as a frame around the window. The major surface of the optically transparent substrate is mounted on the major surface of the driver substrate with the first and second pluralities of external connection/mounting pads being in electrical contact with the mounting pads of the driver substrate. A plurality of driver and controller circuits are mounted on the driver substrate and have data input terminals and further have control signal output terminals connected to the first and second terminals of the light emitting devices for activating the light emitting devices to generate real images in accordance with data signals applied to the data input terminals.

[0013] In the preferred embodiment the external connection/mounting pads of the optically transparent substrate are bump bonded to the mounting pads adjacent an edge of the central portion of the driver substrate to substantially reduce the allowable pitch of the connection/mounting pads. Also, the connection pads on the major surface of the driver substrate are positioned into a matrix of rows and columns to allow a substantially greater number of connection pads in a substantially smaller surface area.

Brief Description of the Drawings

[0014] Referring to the drawings:

FIG. 1 is a greatly enlarged view in top plan of an array of light emitting devices formed on an optically transparent substrate;

FIG. 2 is a simplified cross-sectional view of a single organic electroluminescent element on a glass substrate;

FIG. 3 is an enlarged view in top plan of the optically transparent substrate of FIG. 1 including electrical connections;

FIG. 4 is a greatly enlarged view in top plan of another embodiment of an optically transparent substrate, portions thereof broken away;

FIG. 5 is a greatly enlarged view of a portion of FIG. 4 illustrating portions thereof in greater detail;

FIG. 6 is an exploded view in perspective illustrating the relative positions of the components of an electro-optical package in accordance with the present invention;

FIG. 7 is an enlarged view of the components of FIG. 5, portions thereof broken away, assembled into a complete package;

FIG. 8 is a simplified schematic view of a miniature virtual image display incorporating the package of FIG. 7;

FIGS. 9 and 10 are additional simplified schematic

views, similar to FIG. 8, of other miniature virtual image displays incorporating the package of FIG. 7; FIG. 11 is a view in perspective of a portable communications receiver incorporating the miniature virtual image display of FIG. 8;

FIG. 12 is a simplified view generally as seen from the line 12 - 12 of FIG. 11;

FIG. 13 is a view in perspective of another portable communications receiver incorporating the miniature virtual image display of FIG. 8

FIG. 14 is a simplified view generally as seen from the line 14 - 14 of FIG. 13;

FIG. 15 is a view in perspective illustrating a typical view as seen by the operator of the portable communications receiver of FIG. 11;

FIG. 16 illustrates a schematic diagram of a push-pull array of light emitting diodes;

FIG. 17 is a block diagram of a portion of a driving circuit for the array of FIG. 16;

FIG. 18 illustrates another portion of a driving circuit for the array of FIG. 16; and

FIG. 19 illustrates the array of FIG. 16 and drivers of FIGS. 17 and 18 incorporated into an electronic device.

Description of the Preferred Embodiment

[0015] Referring specifically to FIG. 1, a greatly enlarged view in top plan of an optically transparent substrate 10 having an array 20 of light emitting devices thereon is illustrated. For simplicity of illustration, only a representative portion of optically transparent substrate 10 has been completed. Optically transparent substrate 10 has a major surface 11 with a plurality of light emitting devices 12 formed thereon. Light emitting devices 12 are organic/polymer electroluminescent elements or light emitting diodes. Hereinafter, for simplification of this disclosure, the term organic/polymer will be shortened to "organic". In this embodiment, each light emitting device 12 defines a pixel, with light emitting devices 12 positioned in rows and columns and cooperating to generate a complete real image, when activated, at a central portion 13 of major surface 11.

[0016] Referring specifically to FIG. 2, a simplified and greatly enlarged cross-sectional view of a single organic electroluminescent element 12 on an optically transparent substrate 10, which in this embodiment is glass, is illustrated. Organic electroluminescent element 12 includes a layer 18 of conductive material which serves as the anode of the diode or element 12 in this specific embodiment. An organic layer or layers 19/20 includes one or more layers of polymers or low molecular weight organic compounds. The organic materials that form the layers are chosen for their combination of electrical and luminescent properties, and various combinations of hole transporting, electron transporting, and luminescent materials can be used. In this embodiment, for example, layer 19 is a hole transport layer and layer 20 is

a luminescent electron transport layer. A second layer 21 of conductive material is deposited on the upper surface of layers 19/20 and serves as the cathode in this specific embodiment.

[0017] Generally, either the anode or the cathode must be optically transparent to allow the emission of light therethrough. In this embodiment conductive layer 18 is formed of indium-tin oxide (ITO) which is optically transparent. In some applications a very thin metal film may be used as a transparent conductor instead of the ITO. Also, to reduce the potential required, the cathode is generally formed of a low work function metal/conductors or combination of metals/conductors, at least one of which has a low work function. In this embodiment the cathode is formed of low work function material, such as heavily doped diamond, or the cathode may be a conductive metal incorporating cesium, calcium or the like. The first electrodes, e.g. the anodes, of light emitting devices 12 are connected by conductors 15 to define rows of pixels, and the second electrodes, e.g. the cathodes, of light emitting devices 12 are connected by conductors 17 to define columns of pixels, thereby forming addressable array 20 of light emitting devices 12.

[0018] A list of some possible examples of materials for the organic layer or layers 19/20 of the above described organic electroluminescent element 12 follows. As a single layer of polymer, some examples are: poly(*p*-phenylenevinylene) (PPV); poly(*p*-phenylene) (PPP); and poly[2-methoxy,5-(2'-ethylhexoxy)1,4-phenylenevinylene] (MEH-PPV). As an electron transporting electroluminescent layer between a hole transporting layer or one of the single layer polymers listed above and a low work function metal cathode, an example is: 8-hydroxyquinoline aluminum (ALQ). As an electron transporting material, an example is: 2-(4-tert-butylphenyl)-5-(*p*-biphenyl)-1,3,4-oxadiazole (butyl-PBD). As a hole transport material, some examples are: 4,4'-bis[N-phenyl-N-(3-methylphenyl)amino]biphenyl (TPD); and 1,1-bis(4-di-*p*-tolylaminophenyl)cyclohexane. As an example of a fluorescent that may be used as a single layer or as a dopant to an organic charge transporting layer is coumarin 540, and a wide variety of fluorescent dyes. Examples of low work function metals include: Mg; In, Ca, and Mg:Ag.

[0019] Light emitting devices 12 are formed on optically transparent substrate 10 in a central portion 13 of major surface 11 less than approximately 20 microns in diameter (W), in the embodiment illustrated approximately 10 microns in diameter. Also, the pitch, P, or spacing between centers of light emitting devices 12, is less than approximately 30 microns, and in the present embodiment is 20 microns.

[0020] Referring specifically to FIG. 3, an enlarged view in top plan of a complete, optically transparent substrate 10 is illustrated. In the simplest embodiment, optically transparent substrate 10 is formed of a planar piece of optically transparent material, such as glass, so that at least central portion 13 having array 20 of light

emitting diodes 12 thereon is simply a clear (optically transparent) portion of substrate 10. Central portion 13 is substantially the same size as array 20 of light emitting devices 12 so that the real image generated by light emitting devices 12 in cooperation is completely visible therethrough. A plurality of electrical conductors 31 electrically connect the rows and columns of light emitting devices 12 to a similar plurality of connection pads 33 positioned on the major surface 11 and around the outer periphery of substrate 10. To completely distribute electrical conductors 31 and connection pads 33 around the periphery of optically transparent substrate 10, electrical conductors 31 are attached to alternate horizontal electrical conductors 15 and alternate vertical conductors 17. Thus, the space available between adjacent electrical conductors 31 is 2P, or in this specific embodiment 20 microns.

[0021] By fanning out electrical conductors 31, connection pads 33 can be constructed large enough to provide easy electrical contact thereto. For example, if array 20 of light emitting devices 12 includes 40,000 devices (e.g., 200 x 200) and each device includes an area having a 10 micron diameter with a pitch P of 20 microns, then the area of the central portion 13 of optically transparent substrate 10 will be less than 0.2 inches (1 inch = 2.54 10⁻² m) on a side. Optically transparent substrate 10, in this specific embodiment, is constructed with a central portion 13 approximately 0.2 inches on a side and an outer periphery of 0.5 inches on a side. Thus, the 200 connection pads on each side of the periphery of window frame substrate 25 have approximately 60 microns of pitch available.

[0022] Referring specifically to FIG. 4, a greatly enlarged view in top plan of another embodiment of an optically transparent substrate 40, portions thereof broken away, is illustrated. A portion of substrate 40 is illustrated in a greatly enlarged view in FIG. 5 illustrating portions of optically transparent substrate 40 in greater detail. At least a central optically transparent portion 41 is positioned to receive an array of light emitting diodes thereon as described in conjunction with FIG. 3 and a plurality of electrical conductors 43 are positioned on a major surface 42 of optically transparent substrate 40 and are fanned out from the periphery of central portion 41 into contact with a plurality of connection pads 45. Connection pads 45 are positioned in a matrix of rows and columns on major surface 42 surrounding central portion 41. Generally, it is anticipated that connecting pads 45 can be positioned in the matrix with a pitch in the range of approximately 25 milli-inches to 50 milli-inches to allow sufficient space for electrical conductors 43 to extend therebetween as illustrated. For example, a matrix of connection pads 45 with a pitch of 40 milli-inches allows over 500 connection pads 43 on a one inch by one inch substrate with a central passage 41 of 0.2 inches by 0.4 inches.

[0023] In the instance in which optically transparent substrate 10 is formed of glass, standard thin film met-

allization can be utilized, at least for electrical conductors 31 and connection pads 33, in which layers of metal are deposited by, for example, sputtering. In a typical metallization system, a first layer of chromium is applied by sputtering to operate as an adhesive layer on the glass. A second layer of copper is applied over the chromium to provide the desired electrical conduction and a layer of gold is applied over the copper to provide a barrier and adhesive layer for further connections. It should be understood that the metallization can be either an additive or subtractive method with the patterning and etching being performed by any of the various methods well known in the art to provide the desired final structure.

[0024] In many applications the electrical conductor widths and pad sizes, as well as spacing, may be such that difficulty will be encountered in the fabrication, especially for the substrate. However, glass is an example of an optically transparent substrate material on which 10 to 15 micron wide electrical conductors with a pitch of 40 microns can be fabricated. Also, light emitting diodes 12 are formed in central portion 13 utilizing many common steps.

[0025] An exploded view in perspective illustrating the relative positions of components of an electro-optical package 50 is illustrated in FIG. 6. An enlarged view, portions thereof broken away, of the components of FIG. 6 assembled into a complete electro-optical package 50 is illustrated in FIG. 7. In addition to optically transparent substrate 10, a mounting board, or driver substrate, 55 is included having a plurality of driver and control circuits 57 mounted on an upper major surface thereof. Driver and control circuits 57 generally are formed as smaller integrated circuits which are wire bonded or bump bonded to electrical contacts on the upper major surface of mounting board 55. Mounting board 55 is, for example, a convenient printed circuit board, such as FR4 or the like, and has either bumps 58 of contact material, such as C5 solder, solderable plated metal, or the like, or connecting pins 59 positioned on a lower major surface thereof. In some specific applications, mounting board 55 could be a driver substrate, or single semiconductor chip, having all of the driver and interconnect components integrated thereon. Because the pitch of connection pads 33 on optically transparent substrate 10 is (or can be) relatively large, relatively large bumps 58 or pins 59 can be utilized at this point.

[0026] Bumps 58 are formed of a material that is a relatively good electrical conductor and which can be at least partially melted and reset to form a good physical connection. Material which can be utilized for this purpose includes gold, copper, solder and especially high temperature solder, conducting epoxy, etc. A bump height of up to 80 microns can be formed on a square or round connection/mounting pad with a 20 micron diameter. For smaller pitches, 5 micron diameter copper bumps with a pitch of 10 microns have been formed with a bump height of 20 microns. Also, 15 micron diameter

gold bumps on a 30 micron pitch have been formed to a height of 30 to 45 microns. Some compatible metal may improve the assembly procedures, e.g., gold metallization or gold plating on connection pads 33 of optically transparent substrate 10.

[0027] In the assembly process, optically transparent substrate 10 is positioned so that major surface 11 is up and connection pads 33 are positioned to each contact a separate bump 58 on mounting board 55 when optically transparent substrate 10 is properly registered, as illustrated in FIG. 7. In one fabrication technique, optically transparent substrate 10 includes gold connection pads 33 and is thermo compression bonded to mounting board 55. At the point illustrated in FIG. 6 where optically transparent substrate 10 is substantially completed, optically transparent substrate 10 can be easily tested and/or burned in prior to additional assembly of the package. This ability to provide an intermediate test point can be a substantial cost and time saving in the packaging procedure.

[0028] The final additional component in package 50 is a lens 60 which is fabricated to overlie central portion 13 in optically transparent substrate 10 opposite mounting board 55. Lens 60 is designed to magnify the real image generated by array 20 of light emitting devices 12 on optically transparent substrate 10. In this specific embodiment, lens 60 is affixed to the underside of optically transparent substrate 10 by some convenient optically transparent epoxy or the like and is fabricated so as to simply overlie central portion 13 of optically transparent substrate 10. At least the interstice between mounting board 55 and optically transparent substrate 10 mounted thereon is filled with an optically transparent material 63, which may be any convenient material to provide support and make package 50 a more robust package. Depending upon the material utilized in the formation of array 20 of light emitting diodes 12, a cavity 64 may be formed in mounting board 55 to receive array 20 and the edges of array 20 can be positioned sufficiently close to mounting board 55 to act like an encapsulant dam so that the interstice between the upper surface of array 20 and mounting board 55 is left open or unfilled. Thus, array 20 and mounting board 55 are not physically attached together and different coefficients of expansion will have little or no effect.

[0029] It should be understood that for best results optically transparent substrate 10 and lens 60 should be constructed with indices of refraction which are as close together as practical. If, for example, the index of refraction of optically transparent substrate 10 and lens 60 differs substantially there is a tendency for light to reflect at the interface back into optically transparent substrate 10 and the efficiency of package 50 is reduced. Generally, an index of refraction of approximately 1.5 for optically transparent substrate 10 has been found to be acceptable.

[0030] Thus, an optically transparent substrate of glass or the like, such as substrate 10, has the added

advantage of providing additional environmental protection for array 20 of light emitting diodes 12. Also, because transparent material, such as glass and the like can be provided which has a coefficient of thermal expansion which is the same as, or very close to, the coefficient of thermal expansion of the mounting board 55 and lens 60, substantial improvements in thermal cycling life are achieved with this embodiment.

[0031] It should be understood that the real image generated by the array of light emitting devices 12 on semiconductor substrate 10 is too small to properly perceive (fully understand) with the human eye and generally requires a magnification of at least 10x for comfortable and complete viewing. Lens 60 can be a single lens with additional optical magnification supplied by an external system or lens 60 can include a complete magnification system. Further, lens 60 can be fabricated from glass, plastic or any other material or method well known to those skilled in the optical art. Also, in some applications lens 60 may be a complete external magnification system and may not be physically attached as a portion of package 50. Several examples of optical magnification systems which may be incorporated into lens 60 or applied externally thereto are illustrated in FIGS. 8 through 10, explained below.

[0032] Referring to FIG. 8, a miniature virtual image display 65 is illustrated in a simplified schematic view. Display 65 includes image generation apparatus 66, similar to electro-optical package 50 described above, for providing a real image at an area 67. A fixed optical system 70, in this specific embodiment includes a coherent bundle 71 of optical fibers and a lens system 73. Bundle 71 has a first surface 75 positioned adjacent the area 67 of apparatus 66 and a second surface 76 defined at the opposite end of bundle 71. A single lens, representing lens system 73, is positioned in spaced relation to surface 76 of bundle 71 and, in cooperation with bundle 71, produces a virtual image viewable by an eye 77 spaced from a viewing aperture 78 generally defined by lens system 73.

[0033] As technology reduces the size of the optically transparent substrate and/or the light generating devices on the substrate, greater magnification and smaller lens systems are required. Reducing the size of the lenses while increasing the magnification results in greatly limiting the field of view, substantially reducing eye relief and reducing the working distance of the lens system.

[0034] Surface 75 of bundle 71 is positioned adjacent area 67 of apparatus 66 so as to pick up real images generated by apparatus 66 and transmit the image by way of the optical fibers to surface 76. Bundle 71 is tapered along the length thereof so that the image at surface 76 is larger than the real image at surface 75. The taper in the present embodiment provides an image at surface 76 which is twice as large as the image at surface 75, which is equivalent to a power of two magnification. It will be understood by those skilled in the art

that additional magnification (taper) may be included if desired.

[0035] Lens system 73, represented schematically by the single lens, is mounted in spaced relation from surface 76 of bundle 71 so as to receive the image from surface 76 and magnify it an additional predetermined amount. In the present embodiment, lens system 73 magnifies the image another ten times (10x) so that the real image from apparatus 66 is magnified a total of twenty times. It will of course be understood that the lens system may be adjustable for focus and additional magnification, if desired, or may be fixed in a housing for simplicity. Because the image received by lens system 71 from bundle 71 is much larger than the real image generated by apparatus 66, the lens system does not provide the entire magnification and, therefore, is constructed larger and with less magnification. Because of this larger size, the lens system has a larger field of view and a greater working distance.

[0036] Eye relief is the distance that eye 77 can be positioned from viewing aperture 78 and still properly view the image, which distance is denoted by "d" in FIG. 8. Because of the size of lens system 73, eye relief, or the distance d, is sufficient to provide comfortable viewing and in the present embodiment is great enough to allow a viewer to wear normal eyeglasses, if desired. Because of the improved eye relief the operator can wear normal corrective lenses (personal eyeglasses), and the complexity of focusing and other adjustable features can be reduced, therefore, simplifying the construction of virtual image display 65.

[0037] Referring to FIG. 9, another miniature virtual image display 80 is illustrated in a simplified schematic. In waveguide virtual image display 80, image generation apparatus 81, similar to electro-optical package 50 described above, is affixed to the inlet of an optical waveguide 82 for providing a real image thereto. Waveguide 82 is formed generally in the shape of a parallelogram (side view) with opposite sides, 83, 84 and 85, 86, equal and parallel but not perpendicular to adjacent sides. Side 83 defines the inlet and directs light rays from the real image at apparatus 81 onto a predetermined area on adjacent side 85 generally along an optical path defined by all four sides. Three diffractive lenses 87, 88 and 89 are positioned along adjacent sides 85, 84 and 86, respectively, at three predetermined areas and the magnified virtual image is viewable at an outlet in side 86. This particular embodiment illustrates a display in which the overall size is reduced somewhat and the amount of material in the waveguide is reduced to reduce weight and material utilized.

[0038] Referring to FIG. 10, another specific miniature virtual image display 90 is illustrated in a simplified schematic. In waveguide virtual display 90 an optical waveguide 91 having a generally triangular shape in side elevation is utilized. Image generation apparatus 92, similar to electro-optical package 50 described above, for producing a real image, is affixed to a first

side 93 of optical waveguide 91 and emanates light rays which travel along an optical path directly to a diffractive lens 94 affixed to a second side 95. Light rays are reflected from lens 94 to a diffractive lens 96 mounted on a third side 97. Lens 96 in turn reflects the light rays through a final diffractive lens 98 affixed to the outlet of optical waveguide 91 in side 93, which lens 98 defines a viewing aperture for display 90. In this particular embodiment the sides of display 90 are angularly positioned relative to each other so that light rays enter and leave the inlet and outlet, respectively, perpendicular thereto.

[0039] FIG. 11, illustrates a portable communications receiver 100 having a hand held microphone 101 with a miniature virtual display 102 mounted therein. It will of course be understood that portable communications receiver 100 can be any of the well known portable receivers, such as a cellular or cordless telephone, a two-way radio, a pager, etc. In the present embodiment, for purposes of explanation only, portable communications receiver 100 is a portable two-way police radio, generally the type carried by police officers on duty or security guards. Portable communications receiver 100 includes a control panel 105 for initiating calls and a standard visual display 106, if desired, for indicating the number called or the number calling. Alternately, 106 includes a speaker in addition to or instead of the visual display. Hand held microphone 101 has a push-to-talk switch 107 and a voice pick-up 108.

[0040] Referring to FIG. 12, a simplified sectional view of hand held microphone 101, as seen from the line 12-12, is illustrated. Miniature virtual display 102 includes an electro-optical package similar to package 50, described above, having image generation apparatus 121 for providing a real image to a fixed optical system 120, which in turn produces a virtual image viewable by the operator through an aperture 122. Fixed optical system 120 is constructed to magnify the entire real image from image generation apparatus 121, without utilizing moving parts, so that the virtual image viewable through aperture 122 is a complete frame, or picture, which appears to be very large (generally the size of a printed page) and is easily discernible by the operator. The entire electro-optical package is relatively small and adds virtually no additional space requirements to hand held microphone 101. Optical system 120 is constructed with no moving parts, other than optional features such as focusing, zoom lenses, etc. Further, apparatus 121 requires very little electrical power to generate the real image and, therefore, adds very little to the power requirements of portable communications receiver 100.

[0041] Referring specifically to FIGS. 13 and 14, a second embodiment is illustrated wherein parts similar to those described in relation to FIGS. 11 and 12 are designated with similar numbers with a prime added to the numbers to indicate a different embodiment. In this embodiment a portable communications receiver 100' has a miniature virtual display 102' included in the body

thereof, instead of in a hand held microphone. A hand held microphone is optional and this specific embodiment is desirable for instances where a hand held microphone is not utilized or not available or for use in pagers and the like which do not transmit. Miniature virtual display 102' is basically similar to miniature virtual display 102 of FIGS. 11 and 12 and adds very little to the size, weight, or power consumption of receiver 100'.

[0042] FIG. 15 is a perspective view of hand held microphone 101 illustrating a typical view 125 seen by an operator looking into viewing aperture 122 of miniature virtual image display 102, described in conjunction with FIGS. 11 and 12. View 125 could be, for example, a floor plan of a building about to be entered by the operator (a policeman). In operation, the floor plan is on file at the police station and, when assistance is requested by the policeman, the station simply transmits video representative of the previously recorded plan. Similarly, miniature virtual image display 102 might be utilized to transmit pictures of missing persons or wanted criminals, maps, extremely long messages, etc. Many other variations, such as silent receiver operation wherein the message appears on display 102 instead of audibly, are possible.

[0043] In some applications, light emitting devices 12 and electrical conductors 15 and 17 on optically transparent substrate 10 (FIG. 1) can be very small, micron or even sub-micron size, with the pitch, P, being too small to conveniently operably connect electrical conductors 31 and connecting pads 33 thereto. In such applications the spacing between connecting pads 33 can be increased by forming light emitting diodes 12 into a push-pull array, as described in conjunction with FIGS. 16 through 19, described below.

[0044] Referring specifically to FIG. 16, a push-pull array 210 of light emitting diodes is illustrated. Array 210 includes twenty light emitting diodes formed on a single substrate and arranged into five rows and four columns. Only twenty diodes are illustrated for simplicity and it should be understood that they are representative of the larger arrays described above. Rows of connecting conductors, designated 212 through 216, are positioned on the substrate to correspond, one each, with the diode rows and columns of connecting conductors, designated 220 through 223, are positioned on the substrate to correspond, one each, with the diode columns. The connecting conductors are couple to each anode and cathode of the diodes to provide addressable array 210, with all alternate columns of diodes being reverse connected. Thus, all of the diodes in alternate columns have a cathode connected to the column conductor, i.e. conductors 220 and 222, and all of the diodes in interspersed columns have an anode connected to the column conductors, i.e. conductors 221 and 223. Similarly, in each row, the anode of alternate diodes is connected to the row conductor and the cathode of interspersed diodes is connected to the row conductor. Array 210 is designed for an LED display and, therefore, alternate

columns of diodes are reverse connected, for reasons which will be apparent presently. It will of course be understood that in many applications it may be more convenient to reverse alternate rows of diodes and, therefore, the terms "row" and "column" are generally used interchangeably herein.

[0045] The reverse connected LEDs, as applied to an LED imaging array, is feasible because the LED imaging array is fabricated on an optically transparent substrate with the diodes being internally reverse coupled while retaining an acceptable pitch. This embodiment results in an efficient internal interconnect which requires no additional devices on the LED array and very little additional work during fabrication of the array. Other embodiments exist but require additional devices which are difficult to fabricate and take up additional space.

[0046] Each of the row conductors 212 through 216 have a connection/mounting pad connected thereto. Each alternate column conductor is connected to an adjacent interspersed column conductor to form pairs of column conductors, 220, 221 and 222, 223. Each pair of column conductors has a single connection/mounting pad connected thereto. In push-pull array 210 there are only two connection/mounting pads to all four columns 220 - 223. Thus, in simplified push-pull array 210, the number of external connection/mounting pads has been reduced from the traditional number of nine to only seven. It will be apparent to those skilled in the art that expanding push-pull array 210 to 128 rows and 240 columns will result in a total of $128 \times 240/2 = 248$ total external connections. Thus, the total number of external connections has been reduced by 120 external connections.

[0047] Referring specifically to FIG. 17, a column driving circuit 230 is illustrated, which is designed to be utilized with push-pull array 210. Column driving circuit 230 includes a counter 231 and a plurality of logic circuits 232, only one of which is illustrated. Each logic circuit 232 includes a first logic gate 233, a pair of logic gates 234 and 235 and P and N channel complementary drivers 236 and 237, respectively. In this specific embodiment, counter 231 is a nine bit counter, which may for example be a simple ripple counter. Also, in each logic circuit 232, first logic gate 233 is an eight input NAND gate, and logic gates 234 and 235 are two input NOR gates. Complementary drivers 236 and 237 are P and N channel FETs connected in series between a power source V_{DD} and a reference voltage, which in this instance is ground.

[0048] The first bit output of counter 231 is used as a polarity bit and is applied, in each logic circuit 232, directly to one input terminal of gate 235 and through an inverter to one input terminal of gate 234. The next eight output bits of counter 231 are applied, in each logic circuit 232, to the eight input terminals of gate 233. The eight input terminals are coded so that only one specific combination of output bits will cause gate 233, in each logic circuit 232, to produce an output. The coded con-

nection to each gate 233 can be accomplished in a variety of ways, as for example inverting all inputs in the first logic circuit. In this fashion gate 233 of the first logic circuit would produce an output each time counter 231 produced the output 00000000. Similarly, gate 33 of the next logic circuit is coded so that an output is produced in response to the output 00000001 from counter 231, and so on.

[0049] The output terminal of gate 233 is connected directly to second input terminals of each of gates 234 and 235. An output terminal of gate 234 is inverted and applied to the control gate of driver 236 and an output terminal of gate 235 is applied directly to the control gate of driver 237. The junction of drivers 236 and 237, which is output terminal 238, is connected to the connection/mounting pad of columns 220, 221 of push-pull array 210. In this specific embodiment, the first (least significant) output bit of counter 231 alternately selects gate 235 (a 0 output bit) and, on the next clock pulse, gate 234 (a 1 output bit). Further, the other eight output bits remain constant through this switching of the first bit, so that on the first two clock pulses applied to counter 231: first, driver 237 is activated to ground output terminal 238 and then driver 236 is activated to apply V_{DD} to output terminal 238. Thus, column 220 of push-pull array 210 is addressed on the first clock pulse and column 221 is addressed on the second clock pulse. Because eight output bits of counter 231 are utilized to address the plurality of logic circuits 233, as many as 256 logic circuits can be individually addressed.

[0050] Referring specifically to FIG. 18, a single row driving circuit 240 is illustrated. A similar row driving circuit 240 is provided for each row connection/mounting pad. Each row driving circuit 240 includes a pair of two input terminal gates 241 and 242, two P channel drivers 243 and 244 and two N channel drivers 245 and 246. The P channel drivers 243 and 244 are connected in series between power source V_{DD} and an output terminal 247. The N channel drivers 245 and 246 are connected in series between output terminal 245 and a reference potential, which in this embodiment is ground. P channel driver 243 and N channel driver 246 act as constant current sources and are activated by bias voltages applied to the control gates thereof. An output terminal of gate 241 is connected to the control gate of P channel driver 244 and an output terminal of gate 242 is connected to the control gate of N channel driver 245. One input terminal of each of gates 241 and 242 is connected to a data input terminal 248. The second input terminal of gate 241 is connected through an inverter to the first (least significant) output bit terminal of counter 231 and the second input terminal of gate 242 is connected directly to the first output bit terminal of counter 231.

[0051] In this embodiment, data on terminal 248 consists of a series of 1's and 0's which are indicative of whether a specific LED is to be activated or not. However, since the diodes in interspersed columns 221 and 223 are reverse connected, it is necessary to apply a

potential to the rows which is lower than the potential applied to interspersed columns 221, 223 to activate these diodes. Also, for the alternate columns in which the diodes are not reverse connected, a positive potential must be applied to the selected rows to activate the diodes. Thus, when an alternate column 220 or 222 is selected by the first output bit of counter 231, the same output bit of counter 231 causes gates 241 and 242 of the row driver circuits to select P channel driver 244 which, if the current data bit is a 1, is turned on. Similarly, when an interspersed column 221 or 223 is selected by the first output bit of counter 231, the same output bit of counter 231 causes gates 241 and 242 of the row driver circuits to select N channel driver 245 which, if the current data bit is a 1, is turned on.

[0052] FIG. 19 illustrates an electronic communication device 249 including a simplified block diagram of a complete driving circuit 250 for the array of FIG. 16 to provide a complete display. Communications device 249 is any device which might incorporate a display for displaying messages to be sent and/or received, for example a two way radio or pager. Driving circuit 250 includes counter 231, a plurality of logic circuits 232, a plurality of row driving circuits 240 and a random access memory (RAM) 252 connected to receive video data from an external interface. Counter 231 supplies the polarity bit and the eight bit address to each of the plurality of logic circuits 232, as described above. Thus, each of the columns is sequentially addressed. Counter 231 also supplies the polarity bit to each of the plurality of row drivers 240 and clocks RAM 252 so that data bits are supplied to the plurality of row drivers 240 in synchronism with the address inputs and polarity bit supplied to logic circuits 232 and row drivers 240.

[0053] The number of connection/mounting pads, required to address the columns in the array is reduced by one-half. Further, reversing the connections to interspersed columns is accomplished internally while manufacturing the array so that no additional space and virtually no additional processing steps are required. Also, the internal connections do not require additional devices on the array. The push-pull array requires no additional complicated driving circuits, or additional bus lines in the driving circuits, or expensive external circuitry. The simplicity of the driving circuits is illustrated in the disclosed driving circuits. While specific driving circuits have been disclosed which incorporate the speed and convenience of CMOS circuits, it will be understood that other driving circuits utilizing different conductivity types, etc. may be devised. Further, it will be understood that all of the driving circuits explained with reference to FIGS. 17 through 19 are, or can be, included in driver and control circuits 57, illustrated in FIGS. 6 and 7.

[0054] Thus, the present invention illustrates and teaches integrated electro-optical packages which are not limited in size by the electrical connections and which are substantially smaller than previous integrated packages which perform the same functions. Also, the

present invention illustrates and teaches integrated electro-optical packages which contain arrays of light generating devices with substantially greater numbers of devices than previous integrated packages. Further, the need for interconnect and packaging structures and techniques which can substantially reduce the limitation on size of semiconductor chips and which can reduce the amount of required surface area is substantially reduced, or eliminated, by the present invention.

Claims

1. An integrated electro-optical package (50) characterized by:

an optically transparent substrate (10) with an array (20) of light emitting devices (12) formed thereon and cooperating to generate a complete real image, the light emitting devices (12) being positioned in rows and columns to define all pixels of the real image and operably connected to connection pads (33) formed on the optically transparent substrate (10) and adjacent outer edges thereof;

a driver substrate (55) having upper and lower opposed major surfaces, with the optically transparent substrate being mounted on said lower major surface, said driver substrate defining a central area (64) in the lower major surface substantially coextensive with the real image generated by the array (20) of the optically transparent substrate (10) and mounting pads formed on the lower major surface surrounding the central area (64), the connection pads (33) on said optically transparent substrate (10) being bump bonded (58) to said mounting pads on the lower major surface of the driver substrate (55);

a plurality of driver circuits (57) positioned on the upper major surface of the driver substrate (55) and connected to the array (20) of light emitting devices (12) through electrical connections in the driver substrate, the mounting pads on the lower major surface of the driver substrate (55) and the connection pads (33) on the optically transparent substrate (10); and a lens system (60) mounted to the optically transparent substrate (10) over the complete real image and on a side of the optically transparent substrate (10) opposite the array (20) of light emitting devices (12) to receive and magnify the complete real image and produce an easily viewable virtual image.

2. An integrated electro-optical package as claimed in claim 1 further characterized in that the optically transparent substrate is formed of optically trans-

parent glass.

3. An integrated electro-optical package as claimed in claim 1 further characterized in that the array of light emitting devices includes a plurality of organic electroluminescent elements. 5
4. An integrated electro-optical package as claimed in claim 3 further characterized in that the plurality of organic electroluminescent elements each include a first conductive layer (18) positioned on the major surface of the glass substrate (10), at least one layer of organic material (19, 20) positioned on the first conductive layer (18), and a second conductive layer (21) positioned on the at least one layer of organic material. 10 15
5. An integrated electro-optical package as claimed in claim 4 further characterized in that the at least one layer of organic material on the first conductive layer includes one of a layer of polymer and a layer of low molecular weight organic compound. 20
6. An integrated electro-optical package as claimed in claim 1 further characterized in that the array of light emitting devices formed on the optically transparent substrate (10) is positioned in a push-pull array (210). 25
7. A method of fabricating an electro-optical package (50) characterized by the steps of: 30

forming a plurality of light emitting devices (12) on a major surface (11) of an optically transparent substrate (10), each of the light emitting devices (12) having first and second terminals (18, 21) for activating the light emitting devices (12), the light emitting devices (12) defining a plurality of pixels positioned in rows and columns and cooperating to generate a complete real image, when activated, at a central portion (13) of the major surface (11), the optically transparent substrate (10) further being formed with connection pads (33) adjacent outer edges thereof and outside of the central portion (13) of the major surface (11) with the first terminals (18) of the light emitting devices (12) being connected to a first plurality of said connection pads (33) defining rows of pixels and the second terminals (21) of the light emitting devices (12) being connected to a second plurality of said connection pads (33) defining columns of pixels; 35 40 45 50

forming a plurality of driver circuits (57) having data input terminals and further having control signal output terminals adapted to be connected to the first and second terminals (18, 21) of the light emitting devices (12) for activating the

light emitting devices (12) to generate real images in accordance with data signals applied to the data input terminals; 5

forming a driver substrate (55) with upper and lower opposed major surfaces and forming first electrical connection pads on the upper major surface, second electrical connection pads on the lower major surface and electrical connections in the driver substrate (55) between the first and second electrical connection pads; 10

mounting the optically transparent substrate (10) on the lower major surface of the driver substrate (55) with the second electrical connection pads in electrical contact with the first and second pluralities of connection pads (33) on the major surface of said optically transparent substrate; and 15

mounting the plurality of driver circuits (57) on the upper major surface of the driver substrate (55) with the control signal output terminals electrically contacting the first electrical connection pads; and 20

mounting a lens system (60) to the optically transparent substrate (10) over the complete real image to receive and magnify the complete real image and produce an easily viewable virtual image. 25

8. A method of fabricating an electro-optical package as claimed in claim 7 further characterized in that the step of forming the plurality of light emitting devices on the major surface of the optically transparent substrate includes forming the plurality of light emitting devices on a glass substrate. 30
9. A method of fabricating an electro-optical package as claimed in claim 8 further characterized in that the step of forming the plurality of light emitting devices on the major surface of the optically transparent substrate includes forming organic electroluminescent elements on the glass substrate. 35 40
10. A method of fabricating an electro-optical package as claimed in claim 9 further characterized in that the step of forming the plurality of organic electroluminescent elements on the glass substrate includes the steps of depositing a first conductive layer (18) on the major surface of the glass substrate (10), depositing at least one layer of organic material (19, 20) on the first conductive layer (18), and depositing a second conductive layer (21) on the at least one layer of organic material. 45 50

55 Patentansprüche

1. Integrierte elektro-optische Packung (50), gekennzeichnet durch:

- ein optisch transparentes Substrat (10) mit einem Array (20) von lichtemittierenden Vorrichtungen (12) darauf, die zusammenwirken, so daß sie ein vollständiges reales Bild erzeugen, wobei die lichtemittierenden Vorrichtungen (12) in Reihen und Spalten angeordnet sind, so daß sie alle Pixel des realen Bildes festlegen und zum Betrieb mit Verbindungsanschlüssen (33) auf dem optisch transparenten Substrat (10) und an seinen äußeren Kanten verbunden sind, ein Treibersubstrat (55) mit gegenüberliegenden oberen und unteren Hauptoberflächen, wobei das optisch transparente Substrat auf der unteren Hauptoberfläche des Treibersubstrats aufgebracht ist, wobei das Treibersubstrat einen Zentralbereich (64) auf der unteren Hauptoberfläche festlegt, der im wesentlichen dieselben Ausmaße wie das vom Array (20) des optisch transparenten Substrats (10) erzeugte reale Bild hat, und Montagekontakte auf der unteren Hauptoberfläche, die den Zentralbereich (64) umgeben, wobei die Verbindungskontakte (33) auf dem optisch transparenten Substrat (10) mit den Montagekontakten auf der unteren Hauptoberfläche des Trägersubstrats (55) Bump-kontaktiert (58) sind, mehrere Treiberschaltkreise (57) auf der oberen Hauptoberfläche des Treibersubstrats (55), die über elektrische Verbindungen im Treibersubstrat, die Montagekontakte auf der unteren Hauptoberfläche des Treibersubstrats (55) und die Verbindungskontakte (33) auf dem optisch transparenten Substrat (10) mit dem Array (20) der lichtemittierenden Vorrichtungen (12) verbunden sind, und ein Linsensystem (60), das auf dem optisch transparenten Substrat (10) über dem gesamten realen Bild und auf der dem Array (20) der lichtemittierenden Vorrichtungen (12) gegenüberliegenden Seite des optisch transparenten Substrats (10) angeordnet ist, um das vollständige reale Bild zu empfangen und zu vergrößern und ein gut erkennbares virtuelles Bild zu erzeugen.
2. Integrierte elektro-optische Packung nach Anspruch 1, dadurch gekennzeichnet, daß das optisch transparente Substrat auf einem optisch transparenten Glas aufgebracht ist.
 3. Integrierte elektro-optische Packung nach Anspruch 1, dadurch gekennzeichnet, daß das Array der lichtemittierenden Vorrichtungen mehrere organische elektrolumineszente Elemente umfaßt.
 4. Integrierte elektro-optische Packung nach Anspruch 3, dadurch gekennzeichnet, daß die mehreren organischen elektrolumineszenten Elemente jeweils eine erste leitfähige Schicht (18) auf der Hauptoberfläche des Glassubstrates (10), mindestens eine Schicht organischen Materials (19, 20) auf der ersten leitfähigen Schicht (18) und eine zweite leitfähige Schicht (21) auf der mindestens einen Schicht organischen Materials umfassen.
 5. Integrierte elektro-optische Packung nach Anspruch 4, dadurch gekennzeichnet, daß die mindestens eine Schicht organischen Materials auf der ersten leitfähigen Schicht entweder eine Schicht von Polymeren oder eine Schicht aus einer organischen Verbindung mit niedrigem Molekulargewicht umfaßt.
 6. Integrierte elektro-optische Packung nach Anspruch 1, dadurch gekennzeichnet, daß sich das Array der lichtemittierenden Vorrichtungen auf dem optisch transparenten Substrat (10) in einem Gegentakt-Array (210) befindet.
 7. Verfahren zum Herstellen einer elektro-optischen Packung (50), gekennzeichnet durch die Schritte:

Erzeugen von mehreren lichtemittierenden Vorrichtungen (12) auf einer Hauptoberfläche (11) eines optisch transparenten Substrates (10), wobei jede der lichtemittierenden Vorrichtungen (12) erste und zweite Anschlüsse (18, 20) zum Aktivieren der lichtemittierenden Vorrichtungen (12) aufweist, wobei die lichtemittierenden Vorrichtungen (12) mehrere Pixel festlegen, die in Reihen und Spalten angeordnet sind und die zusammenwirken, um bei Aktivierung an einem zentralen Abschnitt (13) der Hauptoberfläche (11) ein vollständiges reales Bild zu erzeugen, wobei das optisch transparente Substrat (10) außerdem mit Verbindungskontakten (33) erzeugt wird, die nahe seiner Außenkanten und außerhalb des zentralen Teils (13) der Hauptoberfläche (11) liegen, wobei die ersten Anschlüsse (18) der lichtemittierenden Vorrichtungen (12) mit mehreren ersten der Verbindungskontakte (33) verbunden sind, die Pixel-Reihen festlegen, und die zweiten Anschlüsse (21) der lichtemittierenden Vorrichtungen (12) mit mehreren zweiten der Verbindungskontakte (33) verbunden sind, die Pixel-Spalten festlegen,

Erzeugen von mehreren Treiberschaltkreisen (57) mit Dateneingabeanschlüssen und außerdem mit Steuersignalausgangsanschlüssen, die dafür ausgelegt sind, mit den ersten und zweiten Anschlüssen (18, 20) der lichtemittierenden Vorrichtungen (12) zum Aktivieren der lichtemittierenden Vorrichtungen (12) verbunden zu werden, um reale Bilder gemäß den an

die Dateneingangsanschlüsse angelegten Datensignalen zu erzeugen,
Erzeugen eines Treibersubstrates (55) mit gegenüberliegenden oberen und unteren Hauptoberflächen und Erzeugen von ersten elektrischen Verbindungskontakten auf der oberen Hauptoberfläche, von zweiten elektrischen Verbindungskontakten auf der unteren Hauptoberfläche und von elektrischen Verbindungen im Treibersubstrat (55) zwischen den ersten und zweiten elektrischen Verbindungskontakten,

Montieren des optisch transparenten Substrats (10) auf der unteren Hauptoberfläche des Treibersubstrats (55), wobei die zweiten elektrischen Verbindungskontakte elektrisch mit den mehreren ersten und zweiten Verbindungskontakten (33) auf der Hauptoberfläche des optisch transparenten Substrats verbunden sind, und

Montieren der mehreren Treiberschaltkreise (57) auf der oberen Hauptoberfläche des Treibersubstrats (55), wobei die Steuersignalausgangsanschlüsse die ersten elektrischen Verbindungskontakte kontaktieren, und

Montieren eines Linsensystems (69) auf das optisch transparente Substrat (10) über dem gesamten realen Bild, um das vollständige reale Bild zu empfangen und zu vergrößern und um ein gut erkennbares virtuelles Bild zu erzeugen.

8. Verfahren zum Herstellen einer elektro-optischen Packung nach Anspruch 7, dadurch gekennzeichnet, daß der Schritt, die mehreren lichtemittierenden Vorrichtungen auf der Hauptoberfläche des optisch transparenten Substrats zu erzeugen, das Erzeugen der mehreren lichtemittierenden Vorrichtungen auf einem Glasträger umfaßt.
9. Verfahren zum Herstellen einer elektro-optischen Packung nach Anspruch 8, dadurch gekennzeichnet, daß der Schritt, die mehreren lichtemittierenden Vorrichtungen auf der Hauptoberfläche des optisch transparenten Substrats zu erzeugen, das Erzeugen von organischen elektrolumineszenten Elementen auf dem Glasträger umfaßt.
10. Verfahren zum Herstellen einer elektro-optischen Packung nach Anspruch 9, dadurch gekennzeichnet, daß der Schritt, die mehreren organischen elektrolumineszenten Elemente auf dem Glasträger zu erzeugen, die Schritte Aufbringen einer ersten leitfähigen Schicht (18) auf die Hauptoberfläche des Glasträgers (10), Aufbringen mindestens einer Schicht organischen Materials (19, 20) auf die erste leitfähige Schicht (18) und Aufbringen einer zweiten leitfähigen Schicht (21) auf die mindestens

eine Schicht organischen Materials umfaßt.

Revendications

1. Boîtier électro-optique intégré (50), caractérisé par :

un substrat optiquement transparent (10) sur lequel est formé un groupement (20) de dispositifs d'émission de lumière (12) qui coopèrent pour produire une image réelle complète, les dispositifs d'émission de lumière (12) étant positionnés en rangées et en colonnes de façon à définir tous les pixels de l'image réelle et étant fonctionnellement connectés à des plots de connexion (33) formés sur le substrat optiquement transparent (10) et au voisinage des bords extérieurs de celui-ci ;

un substrat d'excitation (55) possédant des surfaces principales supérieure et inférieure opposées, le substrat optiquement transparent étant monté sur ladite surface principale inférieure, ledit substrat d'excitation définissant une aire centrale (64) dans la surface principale inférieure, qui a sensiblement mêmes dimensions que l'image réelle produite par le groupement (20) du substrat optiquement transparent (10) et des plots de montage formés sur la surface principale inférieure entourant l'aire centrale (64), les plots de connexion (33) présents sur ledit substrat optiquement transparent (10) étant soudés par bosses (58) auxdits plots de montage présents sur la surface principale inférieure du substrat d'excitation (55) ;

une pluralité de circuits d'excitation (57) positionnés sur la surface principale supérieure du substrat d'excitation (55) et connectés au groupement (20) de dispositifs d'émission de lumière (12) via des connexions électriques se trouvant dans le substrat d'excitation, les plots de montage présents sur la surface principale inférieure du substrat d'excitation (55) et les plots de connexion (33) présents sur le substrat optiquement transparent (10) ; et

un système de lentilles (60) monté sur le substrat optiquement transparent (10) par dessus l'image réelle complète et du côté du substrat optiquement transparent (10) qui est opposé au groupement (20) de dispositifs d'émission de lumière (12) afin de recevoir et d'agrandir l'image réelle complète et de produire une image virtuelle facilement observable.

2. Boîtier électro-optique intégré selon la revendication 1, caractérisé en outre en ce que le substrat optiquement transparent est formé de verre optiquement transparent.

3. Boîtier électro-optique intégré selon la revendication 1, caractérisé en outre en ce que le groupement de dispositifs d'émission de lumière comporte une pluralité d'éléments électroluminescents organiques.

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4. Boîtier électro-optique intégré selon la revendication 3, caractérisé en outre en ce que les éléments de la pluralité d'éléments électroluminescents organiques comportent chacun une première couche conductrice (18) placée sur la surface principale du substrat de verre (10), au moins une couche de substance organique (19, 20) placée sur la première couche conductrice (18), et une deuxième couche conductrice (21) placée sur la (ou les) couche(s) de substance organique.

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5. Boîtier électro-optique intégré selon la revendication 4, caractérisé en outre en ce que la (ou les) couche(s) de substance organique se trouvant sur la première couche conductrice comportent une (ou des) couche(s) prise(s) dans le groupe que forme une couche de polymère et une couche de composé organique à faible poids moléculaire.

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6. Boîtier électro-optique intégré selon la revendication 1, caractérisé en outre en ce que le groupement de dispositifs d'émission de lumière formés sur le substrat optiquement transparent (10) est disposé suivant un groupement symétrique, ou push-pull, (210).

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7. Procédé de fabrication d'un boîtier électro-optique (50), caractérisé en ce qu'il comprend les opérations suivantes :

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former une pluralité de dispositifs d'émission de lumière (12) sur une surface principale (11) d'un substrat optiquement transparent (10), chacun des dispositifs d'émission de lumière (12) ayant des première et deuxième bornes (18, 21) servant à activer les dispositifs d'émission de lumière (12), les dispositifs d'émission de lumière (12) définissant une pluralité de pixels, ou éléments d'image, positionnés en rangées et en colonnes et coopérant pour produire une image réelle complète, lorsqu'ils sont activés, en une partie centrale (13) de la surface principale (11), le substrat optiquement transparent (10) étant en outre doté de plots de connexion (33) au voisinage de ses bords extérieurs et à l'extérieur de la partie centrale (13) de la surface principale (11), les premières bornes (18) des dispositifs d'émission de lumière (12) étant connectées à une première pluralité desdits plots de connexion (33) définissant des rangées de pixels, et les deuxième bornes (21) des dispositifs d'émission de lumière (12)

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étant connectées à une deuxième pluralité desdits plots de connexion (33) définissant des colonnes de pixels ;

former une pluralité de circuits d'excitation (57) possédant des bornes d'entrée de données et possédant en outre des bornes de sortie de signaux de commande destinées à être connectées aux premières et deuxième bornes (18, 21) des dispositifs d'émission de lumière (12) afin d'activer les dispositifs d'émission de lumière (12) pour produire des images réelles en fonction des signaux de données appliqués aux bornes d'entrée de données ;

former un substrat d'excitation (55) doté de surfaces principales supérieure et inférieure opposées et former des premiers plots de connexion électrique sur la surface principale supérieure, des deuxième plots de connexion électrique sur la surface principale inférieure, et des connexions électriques dans le substrat d'excitation (55) entre les premiers et deuxième plots de connexion électrique ;

monter le substrat optiquement transparent (10) sur la surface principale inférieure du substrat d'excitation (55) de façon que les deuxième plots de connexion électrique soient en contact électrique avec les première et deuxième pluralités de plots de connexion (33) présents sur la surface principale dudit substrat optiquement transparent ;

monter la pluralité de circuits d'excitation (57) sur la surface principale supérieure du substrat d'excitation (55) de façon que les bornes de sortie de signaux de commande soient en contact électrique avec les premiers plots de connexion électrique ; et

monter un système de lentilles (60) sur le substrat optiquement transparent (10) par dessus l'image réelle complète afin de recevoir et d'agrandir l'image réelle complète et de produire une image virtuelle facilement observable.

8. Procédé de fabrication d'un boîtier électro-optique selon la revendication 7, caractérisé en outre en ce que l'opération de formation de la pluralité de dispositifs d'émission de lumière sur la surface principale du substrat optiquement transparent comporte la formation de la pluralité de dispositifs d'émission de lumière sur un substrat de verre.

9. Procédé de fabrication d'un boîtier électro-optique selon la revendication 8, caractérisé en outre en ce que l'opération de formation de la pluralité de dispositifs d'émission de lumière sur la surface principale du substrat optiquement transparent comporte la formation d'éléments électroluminescents organiques sur le substrat de verre.

10. Procédé de fabrication d'un boîtier électro-optique selon la revendication 9, caractérisé en outre en ce que l'opération de formation de la pluralité d'éléments électroluminescents organiques sur le substrat de verre comporte les opérations consistant à déposer une première couche conductrice (18) sur la surface principale du substrat de verre (10), à déposer au moins une couche de substance organique (19, 20) sur la première couche conductrice (18), et à déposer une deuxième couche conductrice (21) sur la (ou les) couche(s) de substance organique.

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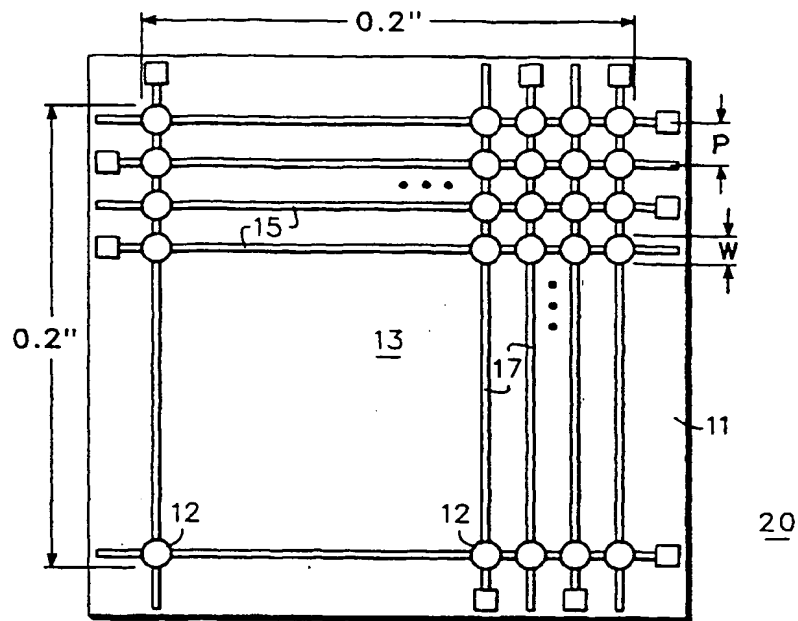


FIG. 1

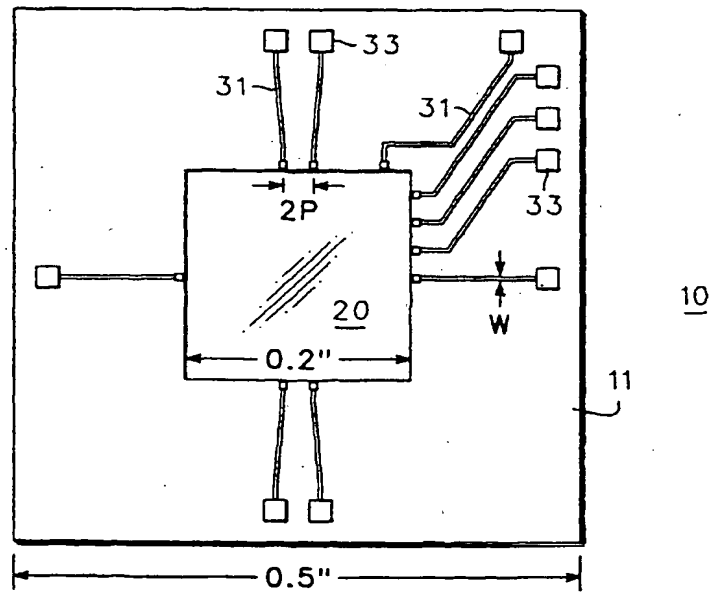


FIG. 3

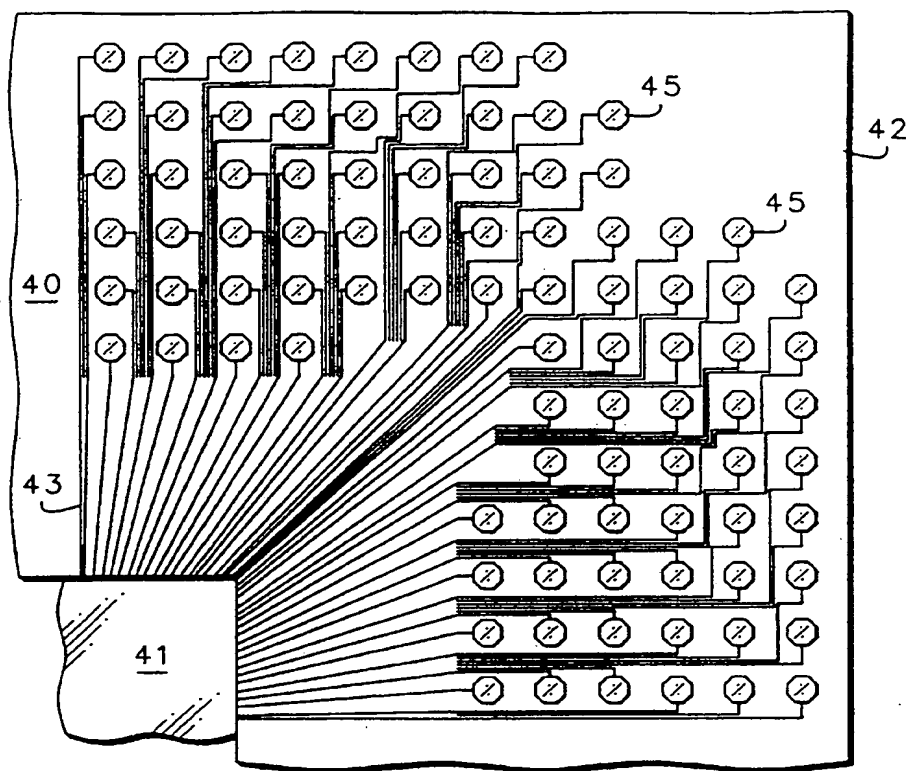


FIG. 4

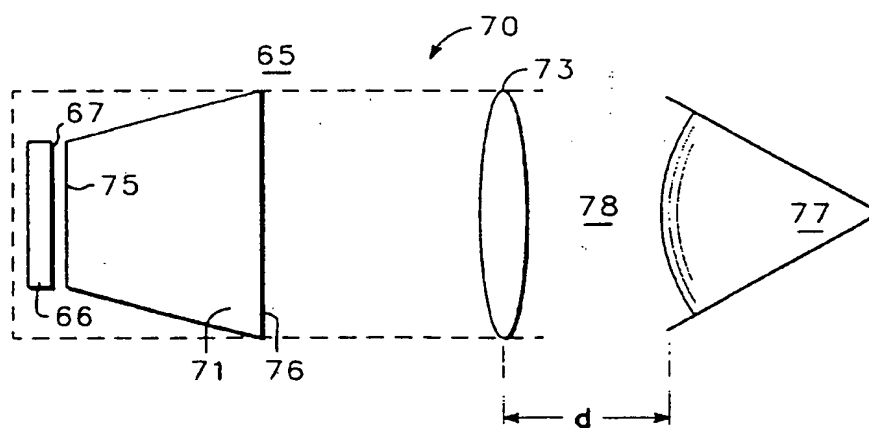


FIG. 8

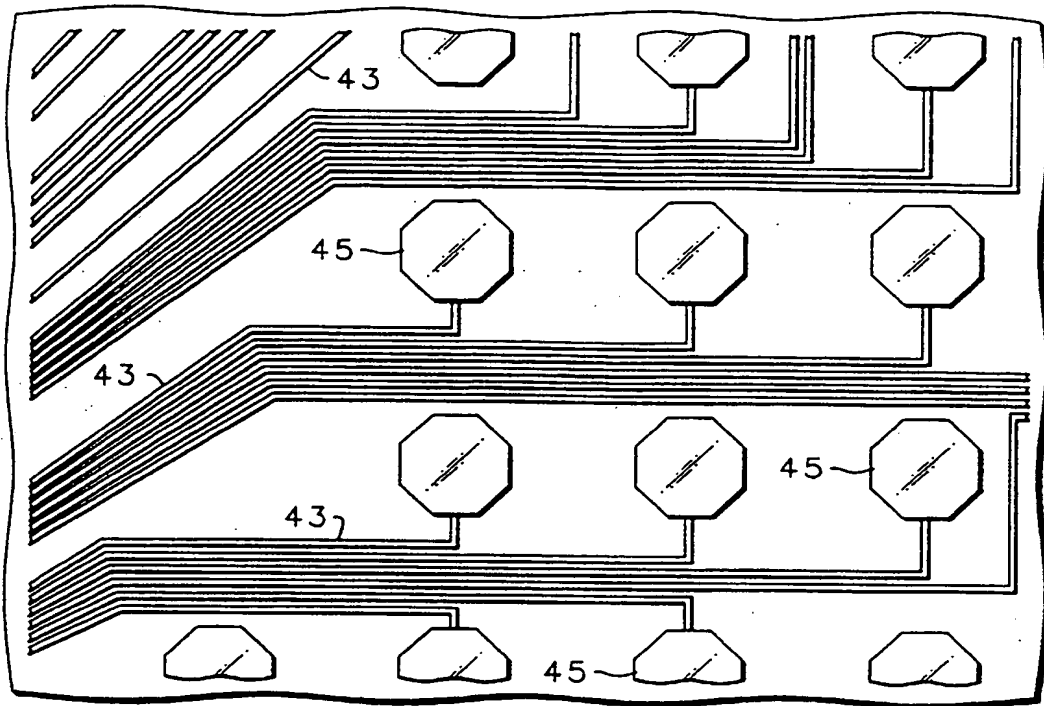


FIG. 5

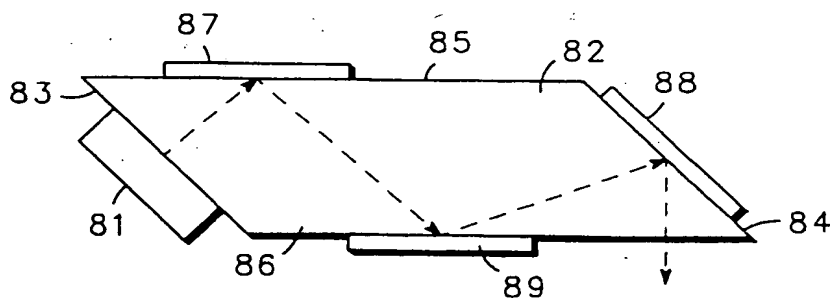


FIG. 9

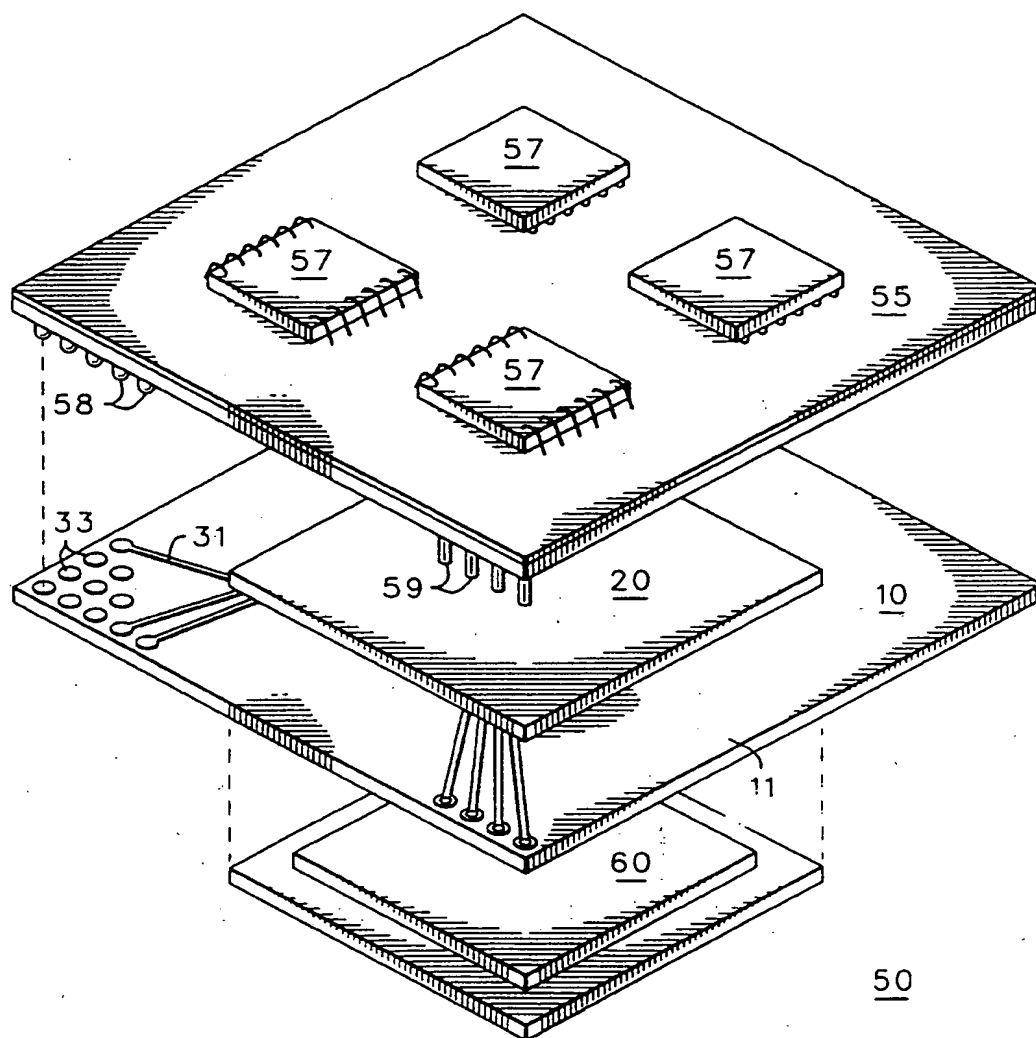


FIG. 6

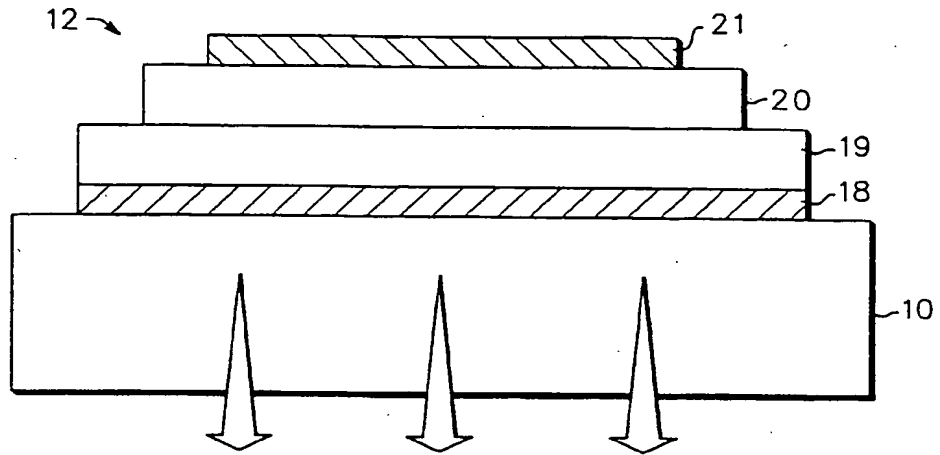


FIG. 2

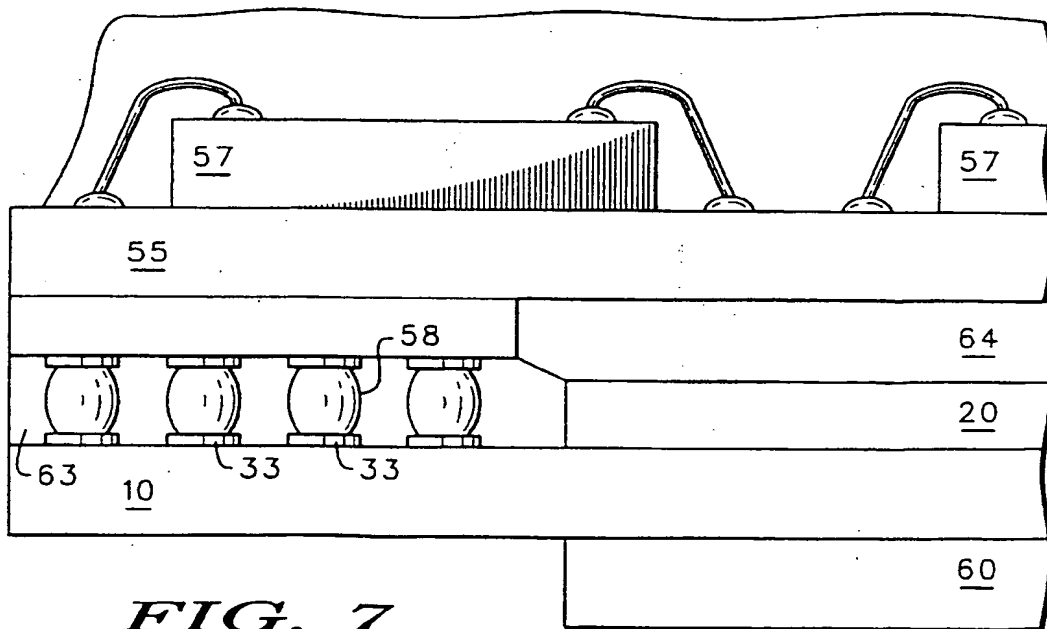


FIG. 7

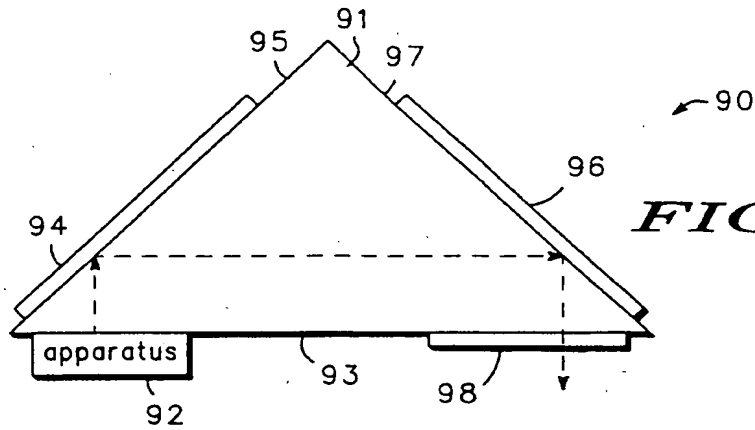
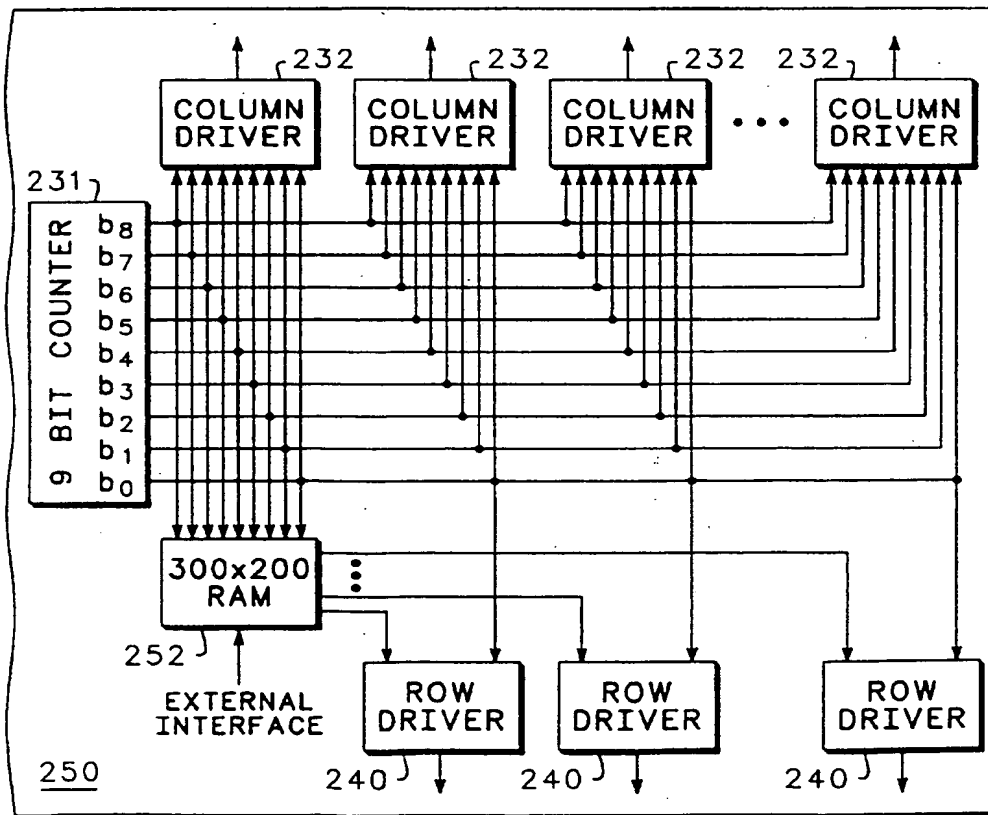


FIG. 10.



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FIG. 12

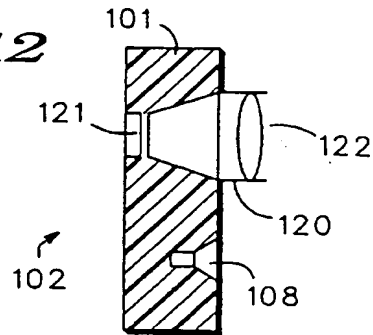


FIG. 11

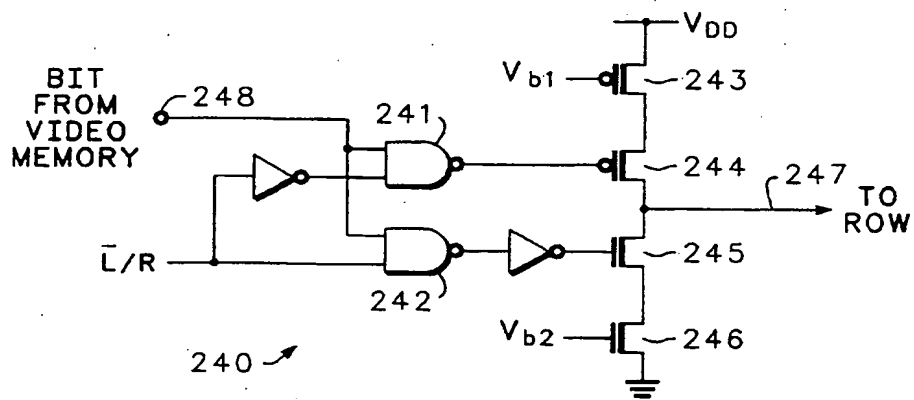
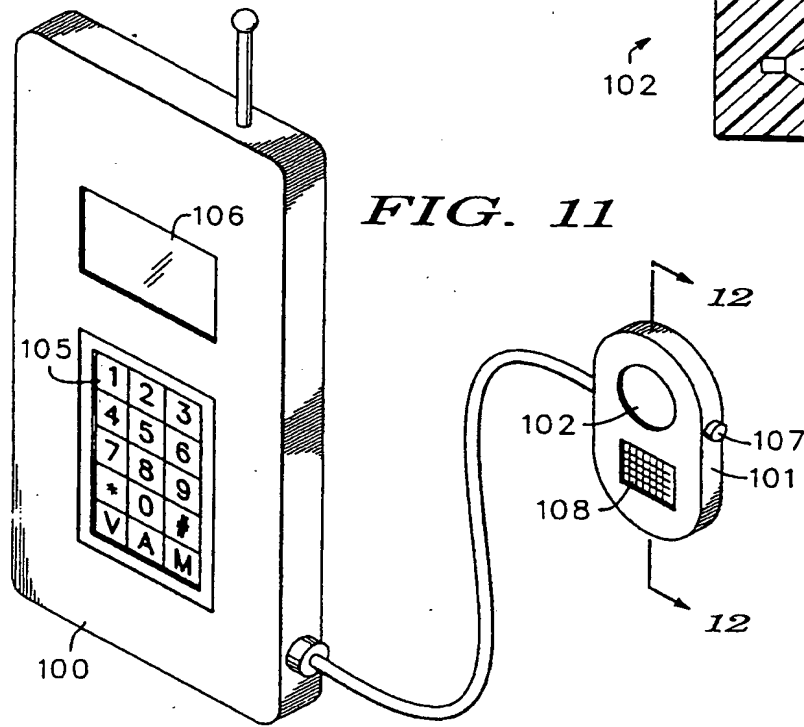


FIG. 18

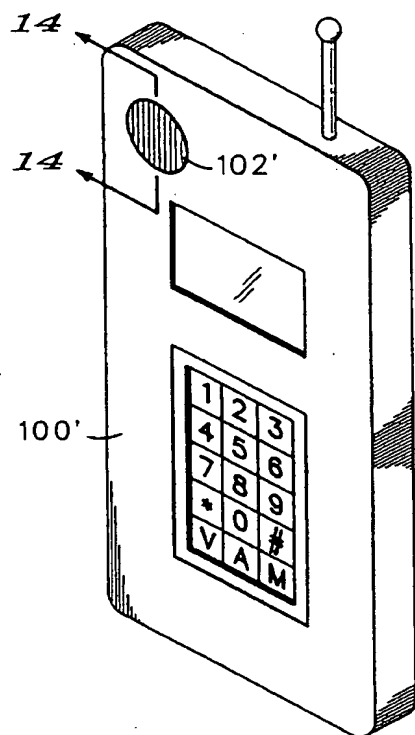


FIG. 13

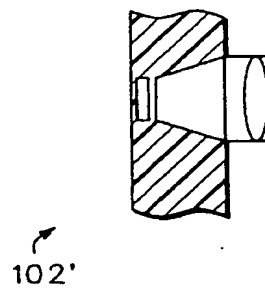


FIG. 14

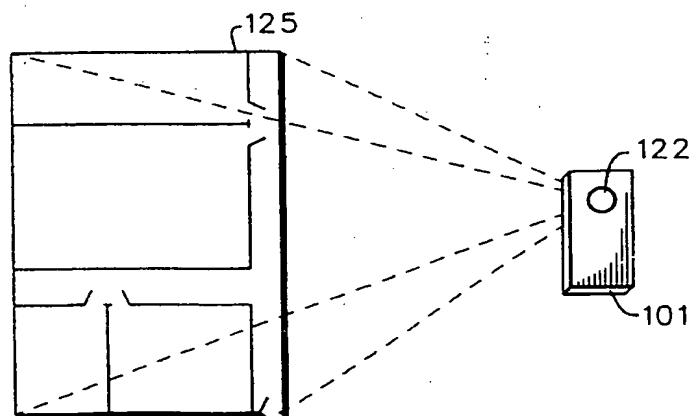


FIG. 15

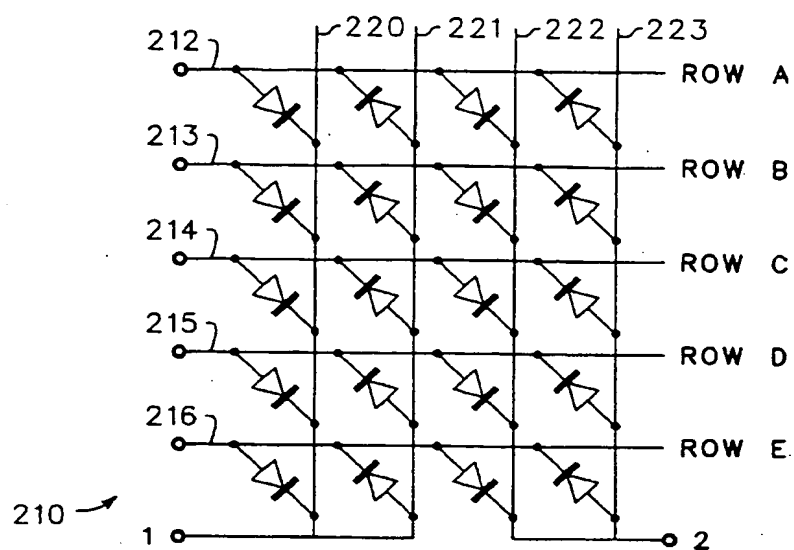


FIG. 16

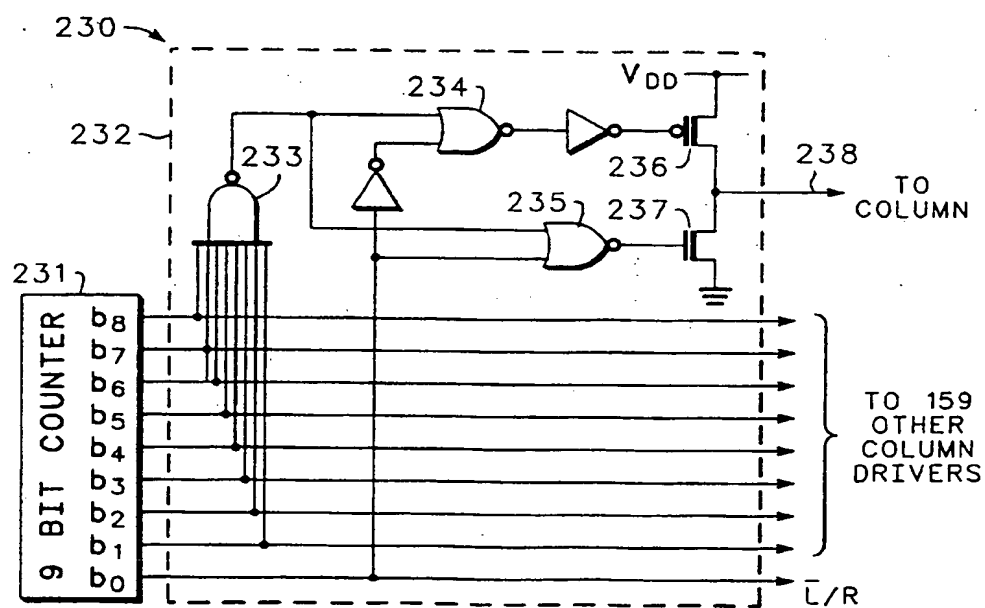


FIG. 17